12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20141015000
Qualification of Additional Assembly/Test locations for select DPY packaged Devices
Change Notification / Sample Request

Date: 10/16/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20141015000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPD1E05U06DPYR	null
TPD1E05U06DPYT	null
TPD1E10B06DPYR	null
TPD1E10B09DPYR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20141015000			**PCN Date:**	10/16/2014
Title:	Qualification of Additional Assembly/Test locations for select DPY packaged Devices				
Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services
Proposed 1st Ship Date:	01/16/2015	**Estimated Sample Availability:**	Date provided upon request		

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of ASE Suzhou (ASEN) and TI Chengdu (CDAT) as an alternate Assembly/Test sites for the devices listed below. Device construction differences are noted as follows:

What	JCET	ASEN	CDAT
Mount Compound	SID#120402002600	**SID#1400230112**	**4221461**
Mold Compound	SID#120903003009	**SID#1800819111**	**4210087**

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
JCET	Assembly Site Origin (22L)	ASO: JCE
ASEN	Assembly Site Origin (22L)	ASO: ASN
CDAT	Assembly Site Origin (22L)	ASO: CDA

Sample product shipping label (not actual product label)

Topside Device marking:
Assembly site code for JCE= F
Assembly site code for ASN=T**
Assembly site code for CDA=8
** - Temporary code. Will change in 2015.

Product Affected			
TPD1E05U06DPYR	TPD1E10B06DPYR	TPD1E10B09DPYR	TPD1E10B09DPYT
TPD1E05U06DPYT	TPD1E10B06DPYT		

TI Information
Selective Disclosure

Qualification Report

New A-T site: ASEN 2-pin DPY multiple devices

Approved 10/02/2014

Product Attributes

Attributes	Qual Device: TPD1E05U06DPYR	Qual Device: TPD1E10B06DPYR	Qual Device: TPD1E10B09DPYR
Assembly Site	ASEN	ASEN	ASEN
Wafer Fab Site	CFAB	CFAB	CFAB
Wafer Fab Process	VDIODE	VDIODE	VDIODE

- QBS: Qual By Similarity
- Qual Device TPD1E05U06DPYR is qualified at -
- Qual Devices qualified at LEVEL1-260C: TPD1E10B06DPYR, TPD1E10B09DPYR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPD1E05U06DPYR	Qual Device: TPD1E10B06DPYR	Qual Device: TPD1E10B09DPYR
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0
SD	Surface Mount Solderability	Pb Free solder	-	-	3/69/0
PD	Physical Dimensions	(Per mechanical drawing)	-	-	3/90/0
ED	Electrical Characterization	(Per Datasheet Parameters)	Pass	Pass	Pass
	Bond Strength	Wires	-	-	3/228/0
FLAM	Flammability (IEC 695-2-2)	--	-	-	3/15/0
FLAM	Flammability (UL 94V-0)	--	-	-	3/15/0
FLAM	Flammability (UL-1694)	--	-	-	3/15/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

Qualification Report

Chengdu A/T Startup X2SON Package (DPY)

Approval date: 10/08/2014

Product Attributes

Attributes	Qual Device: TPD1E10B09DPYR
Assembly Site	CHENGDU
Package Family	X2SON
Flammability Rating	UL 94 V-0
Wafer Fab Site	CFAB
Wafer Fab Process	VDIODE

- QBS: Qual By Similarity
- Qual Device TPD1E10B09DPYR is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPD1E10B09DPYR
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
AC	Autoclave 121C	96 Hours	3/231/0
TC	Temperature Cycle, -65/+150C	500 Cycles	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0
SD	Surface Mount Solderability	Pb Free	3/66/0
PD	Physical Dimensions	(per mechanical drawing)	3/15/0
ED	Electrical Characterization, side by side	-	Pass
MECH	Visual / Mechanical	(per mfg. Site specification)	3/984/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
MQ	Manufacturability (Test)	(per mfg Site specification)	Pass
MSL	Moisture Sensitivity, JEDEC	Level1-260C	3/36/0
	Salt Atmosphere	24 Hours	3/66/0
YLD	FTY and Bin Summary	-	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice e-mail contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com